

# Cross section of CMOS7SF Technology ( 3 levels of metal, wirebond option )

DV post etch

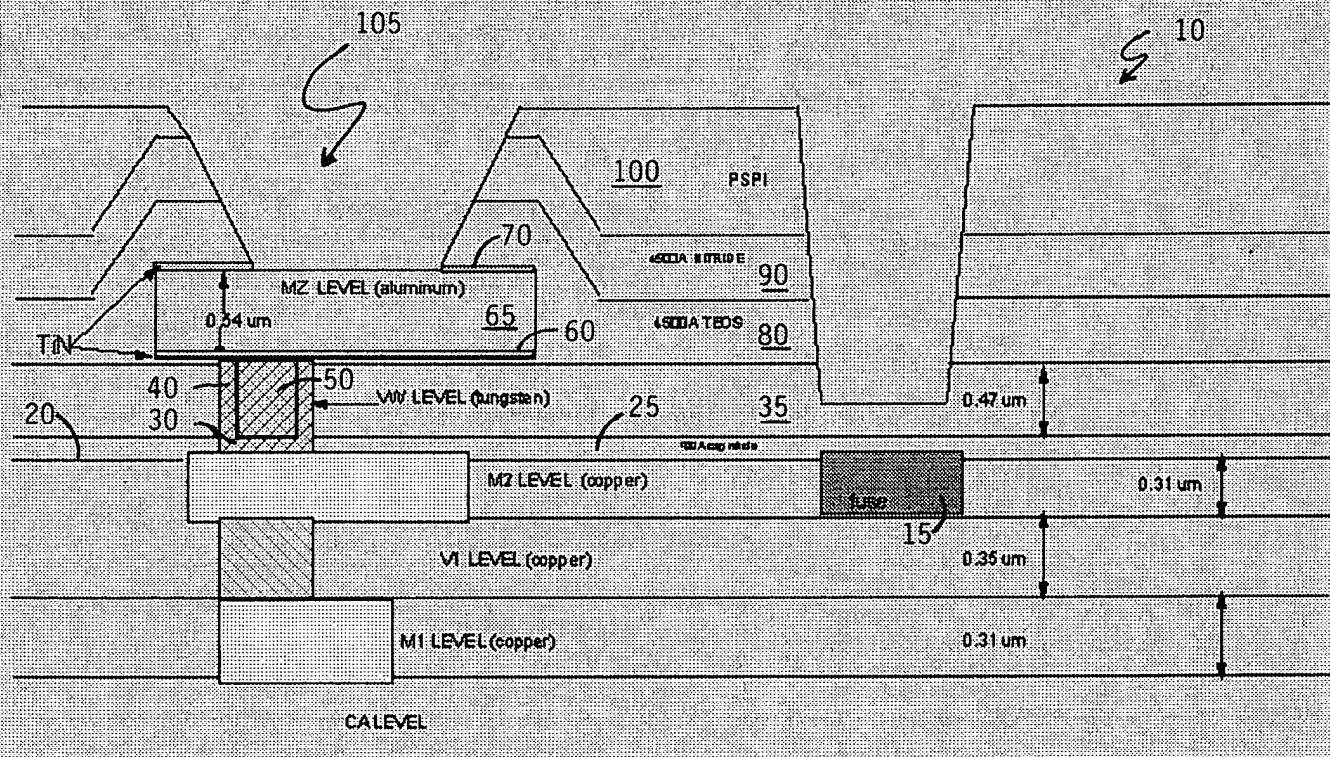


FIGURE 1

## Cross section of CMOS7SF Technology

3 levels of metal , using W via and aluminum last metal

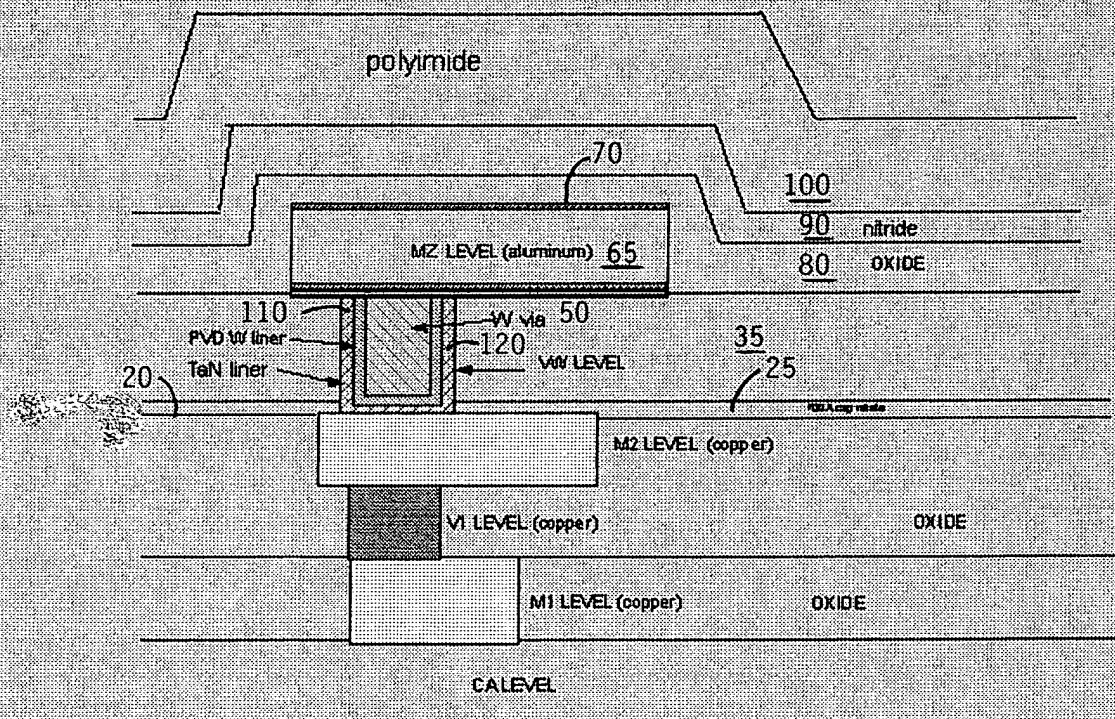


FIGURE 2